

EPIC Technology Meeting on Microelectronics & Photonics – Two Sides of One Coin

Nanoimprint Lithography for Silicon Photonics



EV Group | At A Glance



Leading supplier of wafer processing equipment for the nanotechnology, MEMS and semiconductor markets

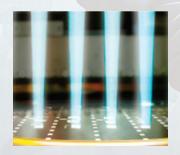
Founded in 1980 by DI Erich and Aya Maria Thallner. More than 1000 employees worldwide

Headquarters in Austria, with fully owned subsidiaries in the USA, Japan, South Korea, China and Taiwan

Recent Developments



GEMINI® FB Hybrid Bonding



EVG[®] MLE™ Maskless Exposure Technology

Nanoimprint Lithography (NIL) Developments



EVG® HERCULES® NIL SmartNIL® HVM Up to 300 mm



EVG® 770 NT S&R NIL System



EVG® 7300 SmartNIL® and WLO Up to 300 mm

EV Group | Focus on Nanoimprint Lithography (NIL)



NIL is a cost-effective and flexible technology to enable nanostructured surfaces as well microstructures on wafer-level

- Volume-proven wafer level imprinting technology (= replication)
- Parallel processing of hundreds or thousands of micro- and nanostructures
- Enables highest resolution at low cost
- Insensitive to shapes, sizes and structures

EVG NIL equipment and dedicated process capabilities



- Step-and-Repeat Mastering
- SmartNIL[®]
- Lens Molding
- → Tools from R&D to fully automated HVM

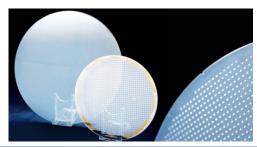


EVG NIL Photonics Competence Center → Innovation Incubator

- Helping to ramp up
- 1.300 m² class 10 100 cleanroom space & application labs









Public

Agenda



- NIL Structures Examples
- NIL Processes
 - Step and Repeat
 - Stamp
- Process Results
- NIL Photonics® Competence Center

Arbitrary 3D Structure

NIL Structure Examples | Broad Range of Possibilities



Diffractive Optical Elements

Holographic Optical Elements

Lightguides

Light Coupling

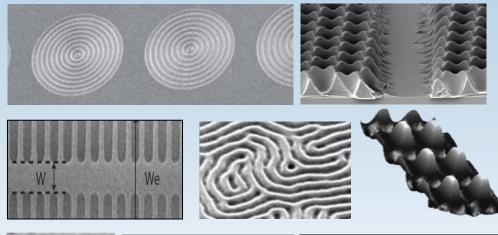
Optical Gratings

Diffusor Optics

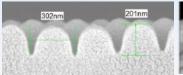
Photonic Crystals

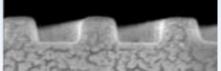
Anti Reflective Structures

Plasmonic Structures











SmartNIL® is shape insensitive and allows efficient replication of complex structures

NIL Applications & Trends | NIL for Silicon Photonics





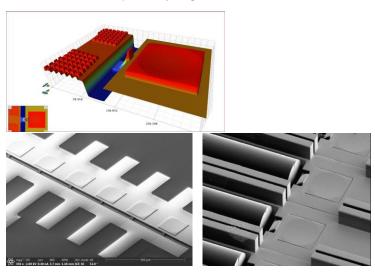
Bridging the gap in SiPh packaging towards wafer level HVM

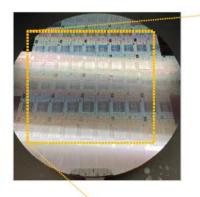
Teramounts PhotonicPlug und PhotonicBump: Done by NIL

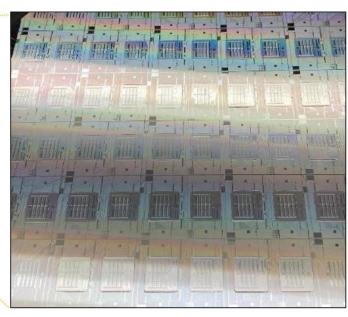
→ Nanoimprint of complex optical microstructures like lenses or mirrors on SiPh wafers

Important

- Pattern fidelity and repeatable → scalability
- Highest alignment accuracy
- Residual layer control → thin and uniform
- Fiber trenches perfectly aligned to the mirrors







PhotonicBump – Imprint inside 20µm on 8" SiPh wafer

NIL for Automotive | PIC waveguide in LiDAR



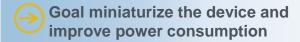


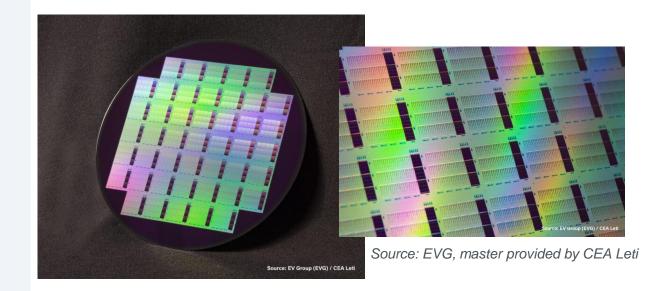
Grant Agreement No. 958472

LiDAR is required for self / autonomous driving cars

Automotive industry needs

- Lower weight
- Better power consumption
- Lowered sensor size and costs



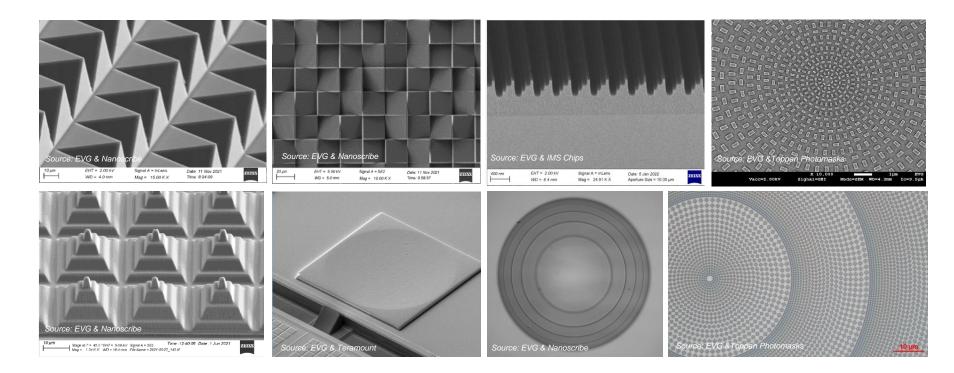




NIL enabled more complex design and miniaturized the system further

NIL Structure Examples | Broad Range of Possibilities



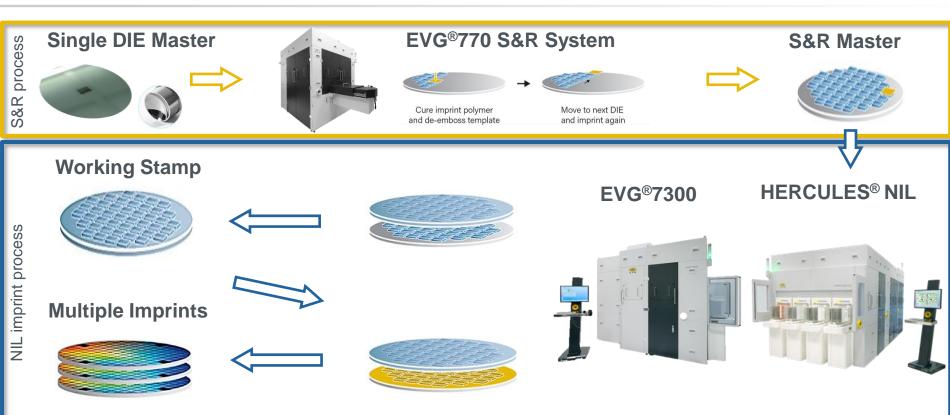




Process capability for nano- and microstructures, also for complex shaped structures - in a single step!

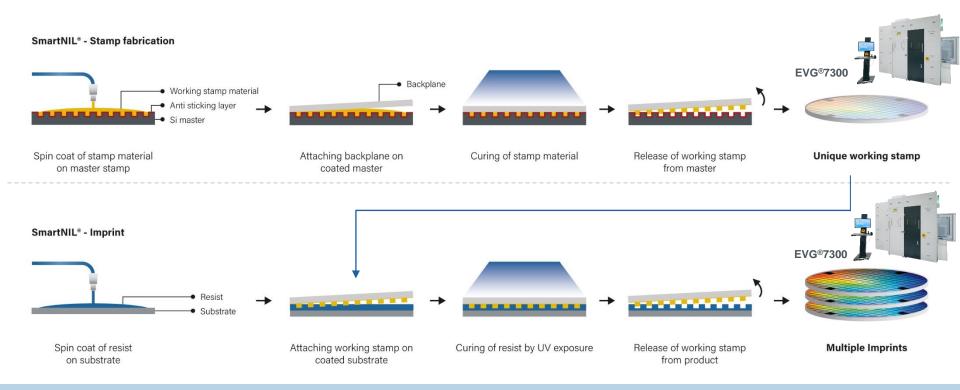
Nanoimprint Lithography | From Master Template to Multiple Imprints





Nanoimprint Lithography | From Master Template to Multiple Imprints







Working stamp manufacturing and imprinting is performed in the same equipment



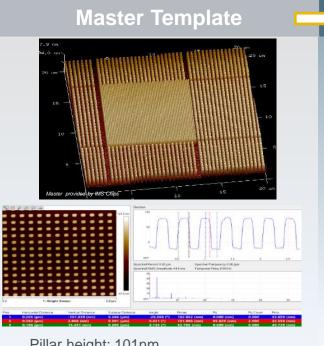


Process Results



S&R and SmartNIL® Results | Process Chain

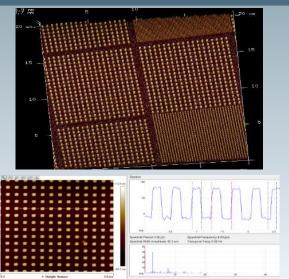




Pillar height: 101nm Pillar Diameter: 186nm

Pitch: 382nm

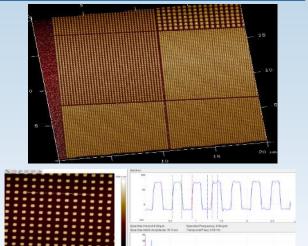




Pillar height: 96nm Pillar Diameter: 176nm

Pitch: 382nm

Final Imprint



Pillar height: 95nm Pillar Diameter: 176nm

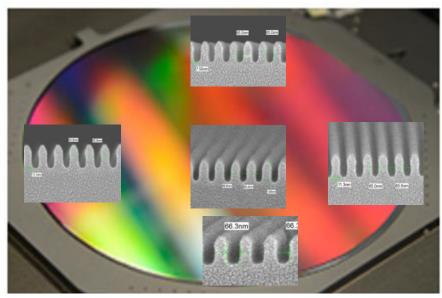
Pitch: 382nm



Stable pattern fidelity over the whole process chain → highly reproducible NIL replications & proven HVM capability

SmartNIL® Results | CD Uniformity





8" Full Area Imprint With Lines and Spaces (Source EVG)

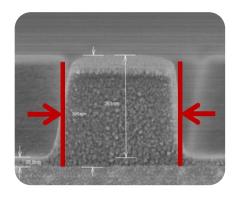


Position	Height	L/S	RLT
Center	179nm	78nm/77nm	10.7nm
12:00	182nm	75nm/75nm	11.7nm
3:00	182nm	75nm/75nm	13.5nm
6.00	181nm	76nm/76nm	8.0nm
9:00	181nm	76nm/76nm	13.5nm

SmartNIL® Results | Pattern Fidelity

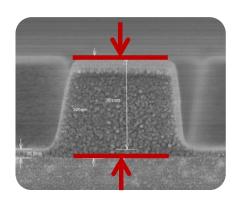


Mean Critical Dimension



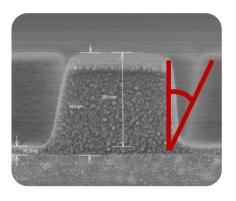
Mean critical dimension
<10nm@ 3δ over all 50
using the same polymer stamp

Height



Height variation of < 20nm@ 3δ over all 50 using the same polymer stamp

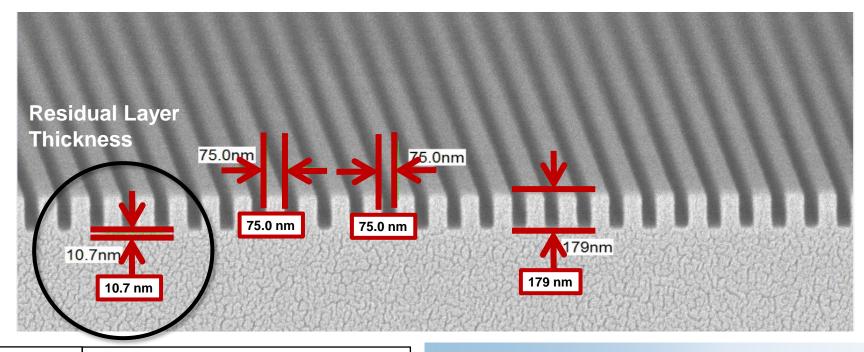
Side Wall Angle



Side wall angle variation < 2,5°@ 3δ over all 50 using the same polymer stamp

SmartNIL® Results | Imprint of L/S Structures





75 nm lines 150 nm pitch 180 nm height

Aspect ratio: 1:2.4

Residual layer thickness:10.7 nm

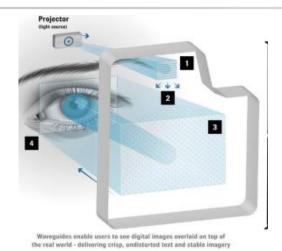


Very small residual layer compared to imprinted structure

No/Minor influence of the residual layer on etching

NIL Applications & Trends | Waveguides for Augmented Reality





Binary Grating

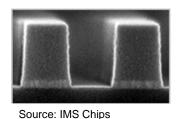


Blazed Grating



Slanted Grating







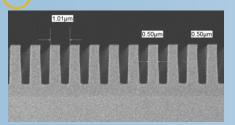


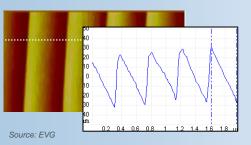
Source: IMS Chips

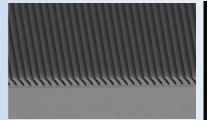
Source: Yole

SmartNIL® Results

Source: Waveoptics









Source: EVG and NILT

Courtesy of Waveoptics

Source: EVG



NIL Photonics® Competence Center



NILPhotonics® Competence Center | Innovation Incubator



"All in one cleanroom" Competence Center at EVG HQ

- R&D and HVM NIL Tools
- S&R Mastering Service
- R&D and Process Development
- Customer Sampling and Demo
- Pilot Line Production
- Supplier Guidance (e.g. Materials, Masters, Substrates)
- Metrology Infrastructure

Over 1.300 m² cleanroom area (class 10 – 100) and application labs



Cleanroom space for rent → quick turnarounds



High quality standards, ISO certified, full documentary and reporting



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Helping customers to ramp up their ideas!



EV Group | Semiconductor Manufacturing for Photonic Devices



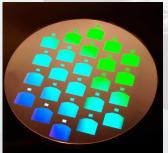
NILPhotonics® Competence Center – A smart way to collaborate for success

Establish decisive manufacturing steps in close collaboration with process and equipment experts

Bridging the gap between photonics R&D and volume manufacturing



Wafer Level Optics & Photonics Packaging

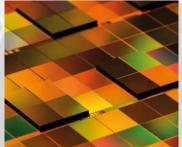


Nanoimprint & S&R Mastering

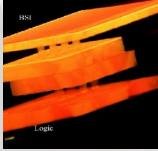


Advanced Resist Processing

Public



Heterogeneous Integration



3D Integration & Hybrid Bonding